# MAX232E Dual RS-232 Driver and Receiver With IEC61000-4-2 Protection

## 1 Features

- Meets or exceeds TIA/RS-232-F and ITU recommendation V.28
- ESD Protection for RS-232 bus pins
  - ±15kV Human-body model (HBM)
  - ±8kV IEC61000-4-2, Contact discharge
  - ±15kV IEC61000-4-2, Air-gap discharge
- Operates from a single 5V power supply with 1µF charge-pump capacitors
- Operates up to 250kbit/s
- Two drivers and two receivers
- Low supply current: 8mA typical

## 2 Applications

- TIA/RS-232-F
- Battery-powered systems
- Terminals
- Modems
- Computers

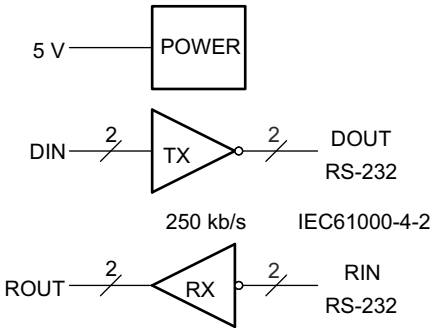
## 3 Description

The MAX232E is a dual driver and receiver that includes a capacitive voltage generator to supply RS-232-F compliant voltage levels from a single 5V supply. Each receiver converts RS-232 inputs to 5V TTL/CMOS levels. This receiver has a typical threshold of 1.3V, a typical hysteresis of 0.5V, and can accept ±30V inputs. Each driver converts TTL/CMOS input levels into TIA/RS-232-F levels.

**Package Information**

| PART NUMBER | PACKAGE(1) | PACKAGE SIZE(2) |
|---|---|---|
| MAX232 | SOIC (16) | 9.9mm × 6mm |
| | SOIC (16) | 10.4mm × 10.3mm |
| | PDIP (16) | 19.3mm × 9mm |
| | SOP (16) | 10.2mm × 7.8 mm |

(1) For more Information, see Section 10.
(2) The package size (length × width) is a nominal value and includes pins, where applicable.






**Logic Diagram (Positive Logic)**

# Table of Contents

# 4 Pin Configuration and Functions

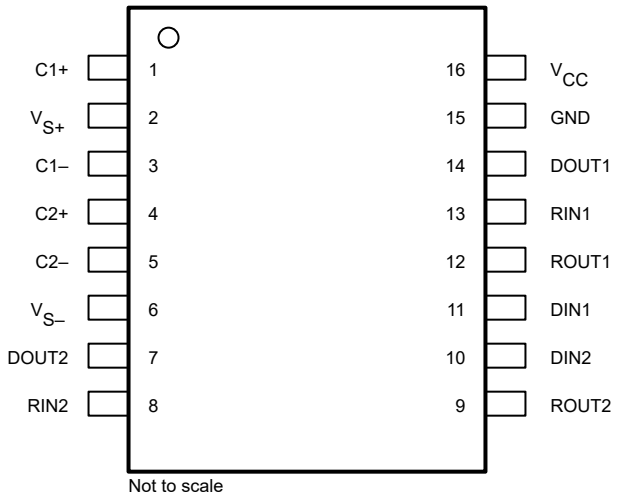



**Figure 4-1. D (SOIC) , DW (SOIC), N (PDIP), or PW (TSSOP) 16-Pin Package (Top View)**

**Table 4-1. Pin Functions**

| PIN | | TYPE | DESCRIPTION |
|---|---|---|---|
| NO. | NAME | | |
| 1 | C1+ | — | Positive lead of C1 capacitor |
| 2 | $V_{S+}$ | O | Positive charge pump output for storage capacitor only |
| 3 | C1– | — | Negative lead of C1 capacitor |
| 4 | C2+ | — | Positive lead of C2 capacitor |
| 5 | C2– | — | Negative lead of C2 capacitor |
| 6 | $V_{S–}$ | O | Negative charge pump output for storage capacitor only |
| 7 | DOUT2 | O | RS-232 line data output (to remote RS-232 system) |
| 8 | RIN2 | I | RS-232 line data input (from remote RS-232 system) |
| 9 | ROUT2 | O | Logic data output (to UART) |
| 10 | DIN2 | I | Logic data input (from UART) |
| 11 | DIN1 | I | Logic data input (from UART) |
| 12 | ROUT1 | O | Logic data output (to UART) |
| 13 | RIN1 | I | RS-232 line data input (from remote RS-232 system) |
| 14 | DOUT1 | O | RS-232 line data output (to remote RS-232 system) |
| 15 | GND | — | Ground |
| 16 | $V_{CC}$ | — | Supply voltage, connect to external 5V power supply |

# 5 Specifications

## 5.1 Absolute Maximum Ratings

over operating free-air temperature range (unless otherwise noted)(1)

| | | | MIN | MAX | UNIT |
|---|---|---|---|---|---|
| $V_{CC}$ | Input supply voltage (2) | | –0.3 | 6 | V |
| $V_{S+}$ | Positive output supply voltage | | $V_{CC}$ – 0.3 | 15 | V |
| $V_{S–}$ | Negative output supply voltage | | –0.3 | –15 | V |
| $V_I$ | Input voltage | Driver | –0.3 | $V_{CC}$ + 0.3 | V |
| | | Receiver | | ±30 | |
| $V_O$ | Output voltage | DOUT | $V_{S–}$ – 0.3 | $V_{S+}$ + 0.3 | V |
| | | ROUT | –0.3 | $V_{CC}$ + 0.3 | |
| | Short-circuit duration | DOUT | Unlimited | | |
| $T_J$ | Operating virtual junction temperature | | | 150 | °C |
| $T_{stg}$ | Storage temperature | | –65 | 150 | °C |

(1) Stresses beyond those listed under *Absolute Maximum Ratings* may cause permanent damage to the device. These are stress ratings only, which do not imply functional operation of the device at these or any other conditions beyond those indicated under *Recommended Operating Conditions*. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
(2) All voltages are with respect to network GND.

## 5.2 ESD Ratings

| | | | | VALUE | UNIT |
|---|---|---|---|---|---|
| $V_{(ESD)}$ | Electrostatic discharge | Human-body model (HBM), per ANSI/ESDA/JEDEC JS-001(1) | Pins 7, 8, 13, and 14 | ±15000 | V |
| | | | Other pins | ±3000 | |
| | | Charged-device model (CDM), per JEDEC specification JESD22-C101(2) | All pins | ±1500 | |
| | | IEC61000-4-2, air-gap discharge | Pins 7, 8, 13, and 14 | ±15000 | |
| | | IEC61000-4-2, contact discharge | | ±8000 | |

(1) JEDEC document JEP155 states that 500V HBM allows safe manufacturing with a standard ESD control process.
(2) JEDEC document JEP157 states that 250V CDM allows safe manufacturing with a standard ESD control process.

## 5.3 Recommended Operating Conditions

| | | | MIN | NOM | MAX | UNIT |
|---|---|---|---|---|---|---|
| $V_{CC}$ | Supply voltage | | 4.5 | 5 | 5.5 | V |
| $V_{IH}$ | High-level input voltage (DIN1, DIN2) | | 2 | | | V |
| $V_{IL}$ | Low-level input voltage (DIN1, DIN2) | | | | 0.8 | V |
| | Receiver input voltage (RIN1, RIN2) | | ±3 | | ±30 | V |
| $T_A$ | Operating free-air temperature | MAX232EC | 0 | | 70 | °C |
| | | MAX232EI | –40 | | 85 | |

## 5.4 Thermal Information

| THERMAL METRIC(1) (2) (3) | | D (SOIC) | DW (SOIC) | N (PDIP) | PW (TSSOP) | UNIT |
|---|---|---|---|---|---|---|
| | | 16 PINS | 16 PINS | 16 PINS | 16 PINS | |
| $R_{\theta JA}$ | Junction-to-ambient thermal resistance | 84.6 | 73.4 | 60.6 | 107.5 | °C/W |
| $R_{\theta JC(top)}$ | Junction-to-case (top) thermal resistance | 43.5 | 35.1 | 48.1 | 38.4 | °C/W |
| $R_{\theta JB}$ | Junction-to-board thermal resistance | 43.2 | 38.3 | 40.6 | 53.7 | °C/W |
| $\psi_{JT}$ | Junction-to-top characterization parameter | 10.4 | 9.4 | 27.5 | 3.2 | °C/W |
| $\psi_{JB}$ | Junction-to-board characterization parameter | 42.8 | 37.7 | 40.3 | 53.1 | °C/W |

(1) For more information about traditional and new thermal metrics, see the *Semiconductor and IC Package Thermal Metrics* application report.
(2) Maximum power dissipation is a function of $T_J(max)$, $R_{\theta JA}$, and $T_A$. The maximum allowable power dissipation at any allowable ambient temperature is $P_D = (T_J(max) – T_A)/R_{\theta JA}$. Operating at the absolute maximum $T_J$ of 150°C can affect reliability.
(3) The package thermal impedance is calculated in accordance with JESD 51-7.

## 5.5 Electrical Characteristics

over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 7-1)

| PARAMETER | | TEST CONDITIONS(1) | | MIN | TYP(2) | MAX | UNIT |
|---|---|---|---|---|---|---|---|
| $I_{CC}$ | Supply current | $V_{CC}$ = 5.5 V | All outputs open, $T_A$ = 25°C | | 8 | 10 | mA |

(1) Test conditions are C1 – C4 = 1µF at $V_{CC}$ = 5V ± 0.5V.
(2) All typical values are at $V_{CC}$ = 5 V and $T_A$ = 25°C.

## 5.6 Electrical Characteristics: Driver

over recommended ranges of supply voltage and operating free-air temperature range

| PARAMETER | | | TEST CONDITIONS(1) | | MIN | TYP(2) | MAX | UNIT |
|---|---|---|---|---|---|---|---|---|
| $V_{OH}$ | High-level output voltage | DOUT | $R_L$ = 3 kΩ to GND | | 5 | 7 | | V |
| $V_{OL}$ | Low-level output voltage(3) | DOUT | $R_L$ = 3 kΩ to GND | | | –7 | –5 | V |
| $r_o$ | Output resistance | DOUT | $V_{S+}$ = $V_{S–}$ = 0, | $V_O$ = ±2 V | 300 | | | Ω |
| $I_{OS}$ (4) | Short-circuit output current | DOUT | $V_{CC}$ = 5.5 V, | $V_O$ = 0 | | ±10 | | mA |
| $I_{IS}$ | Short-circuit input current | DIN | $V_I$ = 0 | | | | 200 | µA |

(1) Test conditions are C1 – C4 = 1µF at $V_{CC}$ = 5V ± 0.5V.
(2) All typical values are at $V_{CC}$ = 5V and $T_A$ = 25°C.
(3) The algebraic convention, in which the least-positive (most negative) value is designated minimum, is used in this data sheet for logic voltage levels only.
(4) Not more than one output should be shorted at a time.

## 5.7 Electrical Characteristics: Receiver

over recommended ranges of supply voltage and operating free-air temperature range

| PARAMETER | | | TEST CONDITIONS(1) | | MIN | TYP(2) | MAX | UNIT |
|---|---|---|---|---|---|---|---|---|
| $V_{OH}$ | High-level output voltage | ROUT | $I_{OH}$ = –1mA | | 3.5 | | | V |
| $V_{OL}$ | Low-level output voltage | ROUT | $I_{OL}$ = 3.2mA | | | | 0.4 | V |
| $V_{IT+}$ | Receiver positive-going input threshold voltage | RIN | $V_{CC}$ = 5V | $T_A$ = 25°C | | 1.7 | 2.4 | V |
| $V_{IT–}$ | Receiver negative-going input threshold voltage | RIN | $V_{CC}$ = 5V | $T_A$ = 25°C | 0.8 | 1.2 | | V |
| $V_{hys}$ | Input hysteresis voltage | RIN | $V_{CC}$ = 5V | | 0.2 | 0.5 | 1 | V |
| $r_i$ | Receiver input resistance | RIN | $V_{CC}$ = 5V | $T_A$ = 25°C | 3 | 5 | 7 | kΩ |

(1) Test conditions are C1 – C4 = 1µF at $V_{CC}$ = 5V ± 0.5V.
(2) All typical values are at $V_{CC}$ = 5V and $T_A$ = 25°C.

## 5.8 Switching Characteristics: Driver

$V_{CC}$ = 5V, $T_A$ = 25°C

| PARAMETER | | TEST CONDITIONS(1) | MIN | TYP | MAX | UNIT |
|---|---|---|---|---|---|---|
| SR | Driver slew rate | $R_L$ = 3kΩ to 7kΩ, See Figure 6-2 | | | 30 | V/µs |
| SR(t) | Driver transition region slew rate | $R_L$ = 3kΩ, $C_L$ = 2.5nF<br>See Figure 6-3 | | 3 | | V/µs |
| | Data rate | One DOUT switching | | 250 | | kbit/s |

(1) Test conditions are C1 – C4 = 1µF at $V_{CC}$ = 5V ± 0.5V.

## 5.9 Switching Characteristics: Receiver

$V_{CC}$ = 5V, $T_A$ = 25°C (see Figure 6-1)

| PARAMETER | | TEST CONDITIONS(1) | TYP | UNIT |
|---|---|---|---|---|
| $t_{PLH(R)}$ | Receiver propagation delay time, low- to high-level output | $C_L$ = 50pF | 500 | ns |
| $t_{PHL(R)}$ | Receiver propagation delay time, high- to low-level output | $C_L$ = 50pF | 500 | ns |

(1) Test conditions are C1 – C4 = 1µF at $V_{CC}$ = 5V ± 0.5V.

## 5.10 Typical Characteristics

$T_A$ = 25 °C

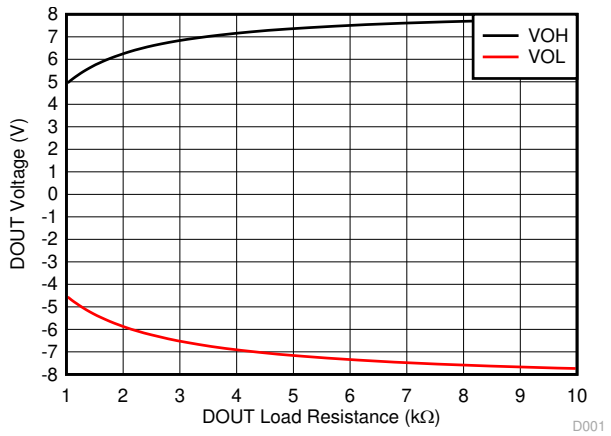



**Figure 5-1. Driver Output Voltage vs Load Resistance**

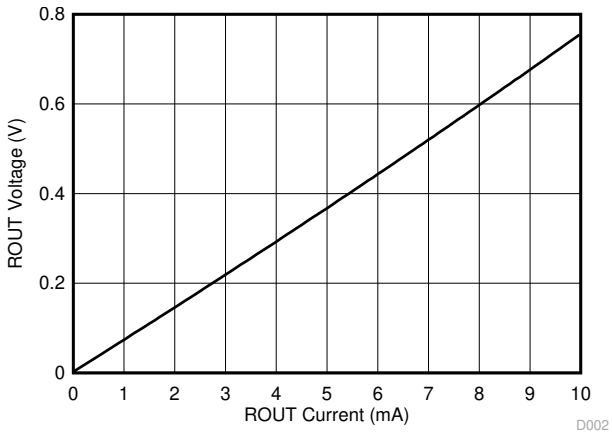



**Figure 5-2. Receiver Low Output Voltage vs Load Current**

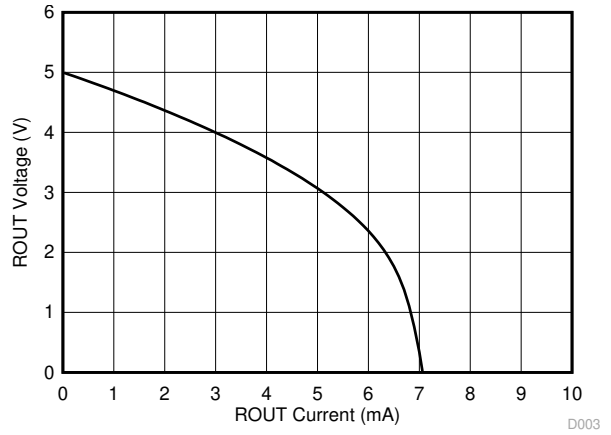



**Figure 5-3. Receiver High Output Voltage vs Load Current**

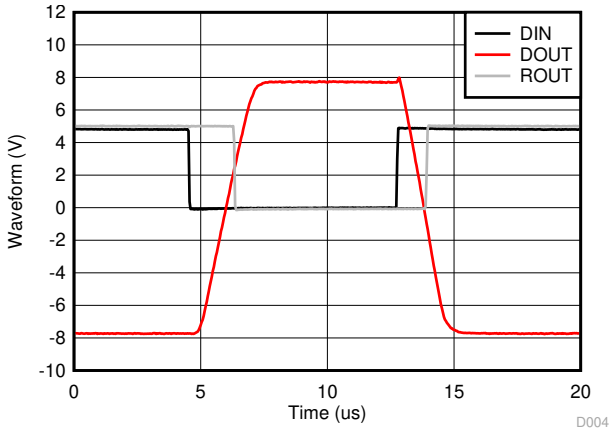
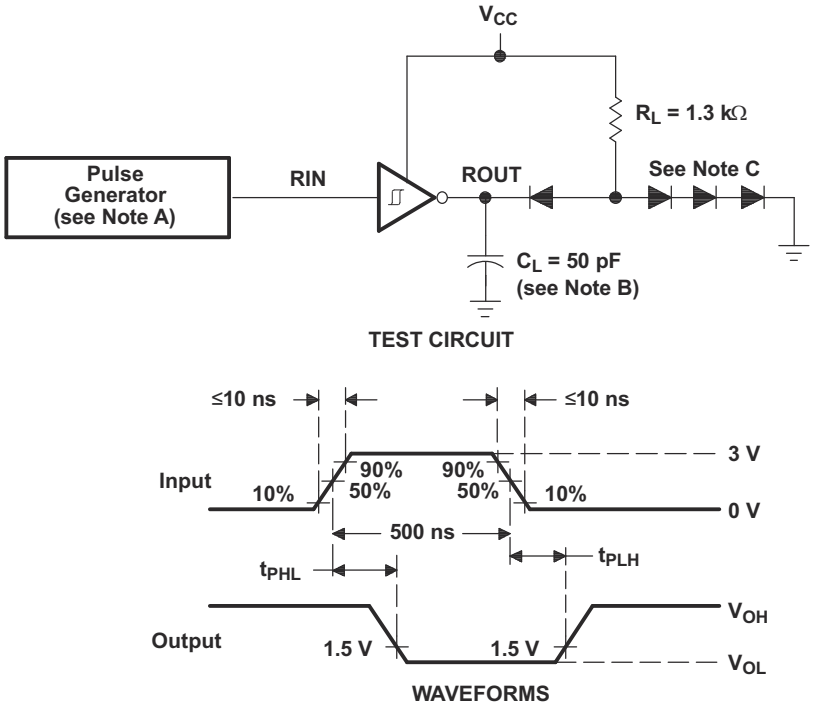
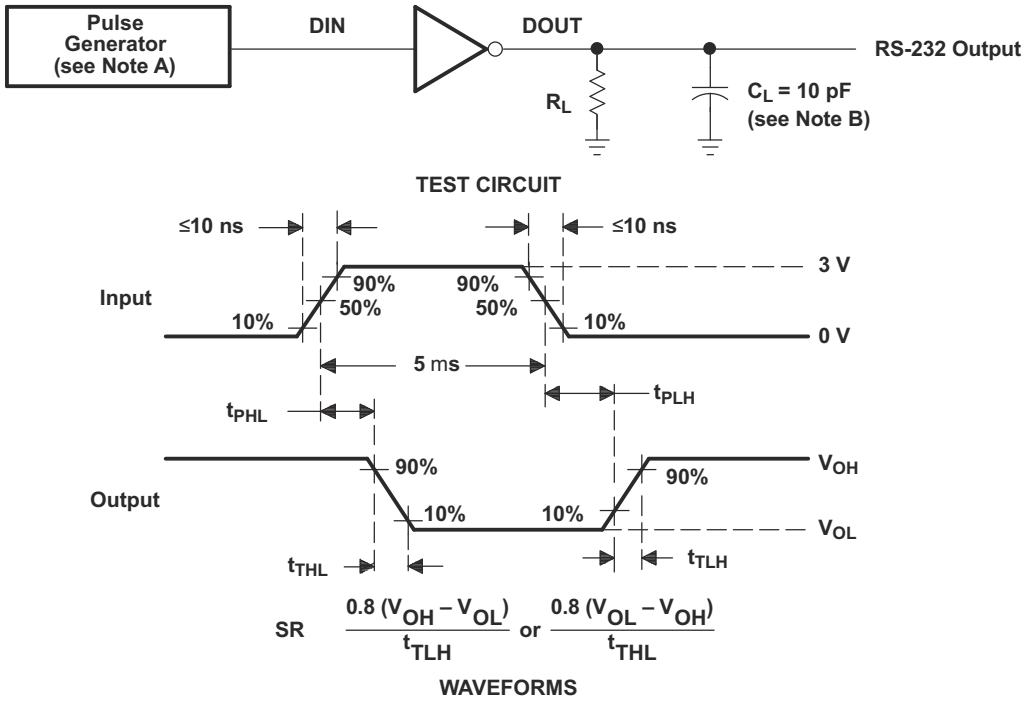



**Figure 5-4. Loopback Waveforms Data Rate 120 kbit/s**




A. The pulse generator has the following characteristics: $Z_O$ = 50Ω, duty cycle ≤ 50%.
B. $C_L$ includes probe and jig capacitance.
C. All diodes are 1N3064 or equivalent.

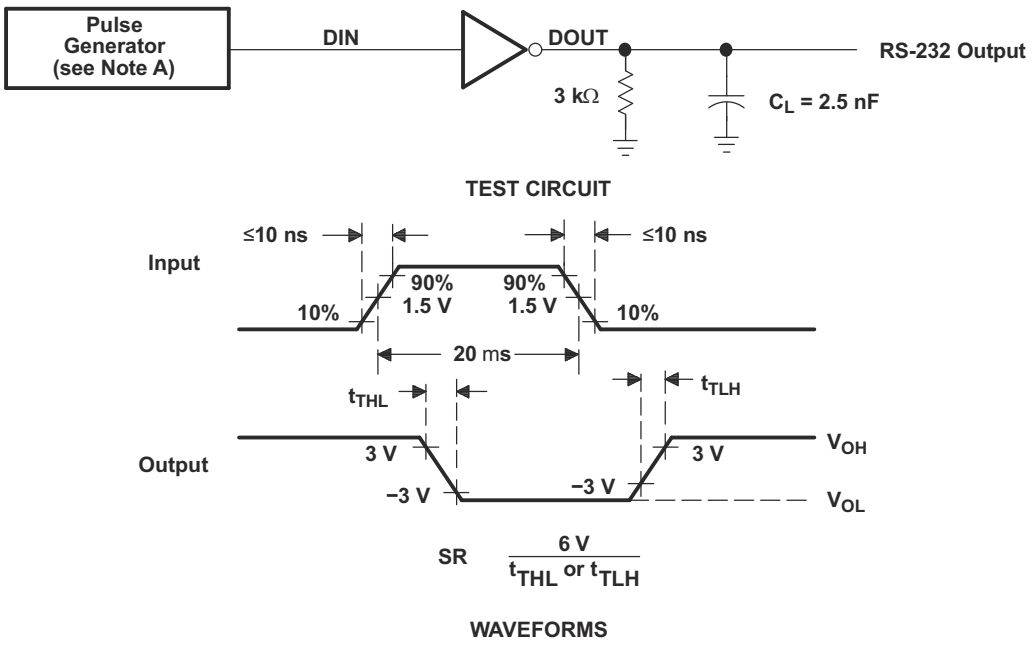
**Figure 6-1. Receiver Test Circuit and Waveforms for $t_{PHL}$ and $t_{PLH}$ Measurements**




A. The pulse generator has the following characteristics: $Z_O$ = 50Ω, duty cycle ≤ 50%.

B. $C_L$ includes probe and jig capacitance.

**Figure 6-2. Driver Test Circuit and Waveforms for $t_{PHL}$ and $t_{PLH}$ Measurements (5-µs Input)**




A. The pulse generator has the following characteristics: $Z_O$ = 50Ω, duty cycle ≤ 50%.

**Figure 6-3. Test Circuit and Waveforms for $t_{THL}$ and $t_{TLH}$ Measurements (20-µs Input)**

# 6 Detailed Description

## 6.1 Overview

The MAX232E is a dual driver and receiver that includes a capacitive voltage generator using four capacitors to supply TIA/EIA-232-F voltage levels from a single 5V supply. All RS-232 pins have 15kV HBM and IEC61000-4-2 Air-Gap discharge protection. RS-232 pins also have 8kV IEC61000-4-2 contact discharge protection. Each receiver converts TIA/EIA-232-F inputs to 5V TTL/CMOS levels. These receivers have shorted and open fail safe. The receiver can accept up to ±30V inputs and decode inputs as low as ±3 V. Each driver converts TTL/CMOS input levels into TIA/EIA-232-F levels. Outputs are protected against shorts to ground.

## 6.2 Functional Block Diagram

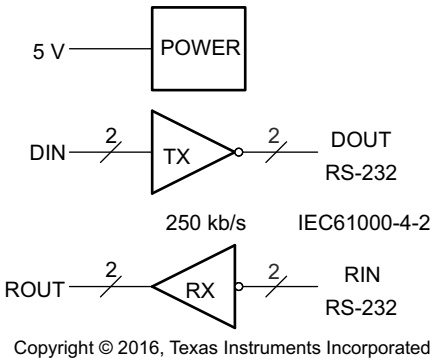




**Figure 6-1. Logic Diagram (Positive Logic)**

## 6.3 Feature Description

### 6.3.1 Power

The power block increases and inverts the 5V supply for the RS-232 driver using a charge pump that requires four 1µF external capacitors.

### 6.3.2 RS-232 Driver

Two drivers interface standard logic level to RS-232 levels. Internal pullup resistors on DIN inputs ensures a high input when the line is high impedance.

### 6.3.3 RS-232 Receiver

Two receivers interface RS-232 levels to standard logic levels. An open or shorted to ground input results in a high output on ROUT.

## 6.4 Device Functional Modes

### 6.4.1 $V_{CC}$ Powered by 5V

The device is in normal operation.

### 6.4.2 $V_{CC}$ Unpowered

When MAX232E is unpowered, it can be safely connected to an active remote RS-232 device.

### 6.4.3 Truth Tables

Table 6-1 and Table 6-2 list the functions of this device.

**Table 6-1. Function Table for Each Driver**

| INPUT DIN(1) | OUTPUT DOUT |
|---|---|
| L | H |
| H | L |

(1) H = high level, L = low level

**Table 6-2. Function Table for Each Receiver**

| INPUT RIN(1) | OUTPUT ROUT |
|---|---|
| L | H |
| H | L |
| Open | H |

(1) H = high level, L = low level, Open = input disconnected or connected driver off

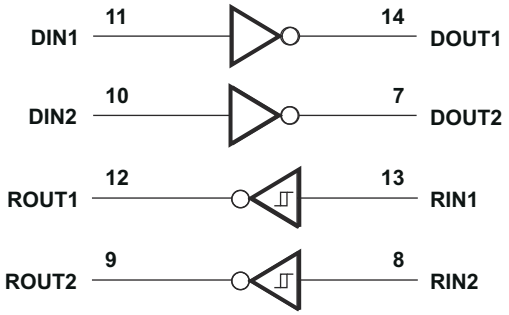



**Figure 6-2. Logic Diagram (Positive Logic)**

# 7 Applications and Implementation

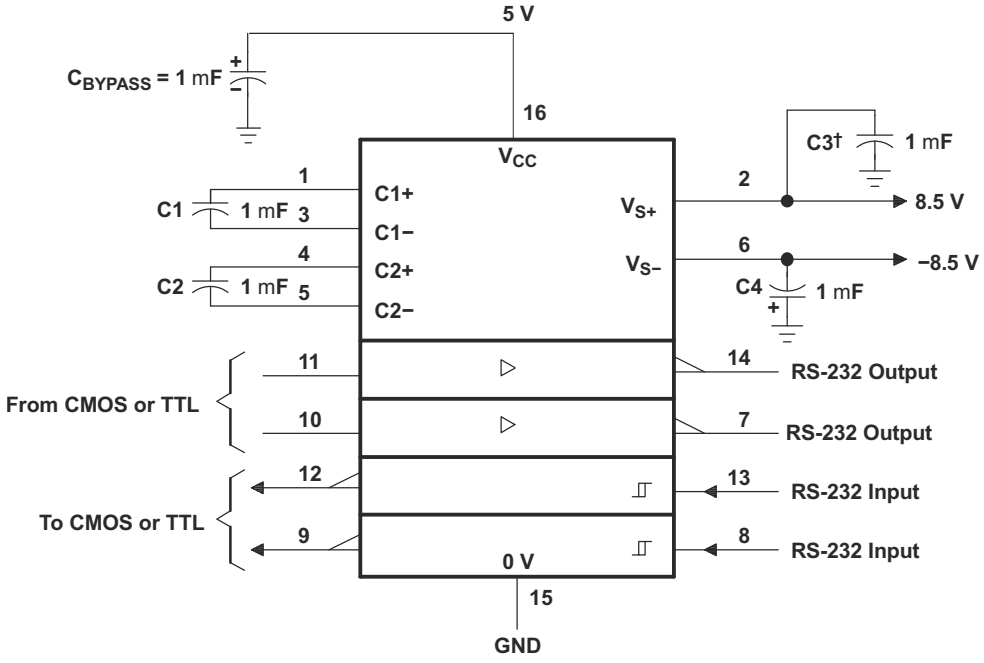
**Note**

Information in the following applications sections is not part of the TI component specification, and TI does not warrant its accuracy or completeness. TI's customers are responsible for determining suitability of components for their purposes, as well as validating and testing their design implementation to confirm system functionality.

## 7.1 Application Information

For proper operation add capacitors as shown in Figure 7-1. Pins 9 through 12 connect to UART or general purpose logic lines. RS-232 lines on pins 7, 8, 13, and 14 connect to a connector or cable.

## 7.2 Typical Application




† C3 can be connected to $V_{CC}$ or GND.



Resistor values shown are nominal.

Nonpolarized ceramic capacitors are acceptable. If polarized tantalum or electrolytic capacitors are used, they should be connected as shown.

**Figure 7-1. Typical Operating Circuit**

### 7.2.1 Design Requirements

- $V_{CC}$ minimum is 4.5V and maximum is 5.5V.
- Maximum recommended bit rate is 250kbit/s.

### 7.2.2 Detailed Design Procedure

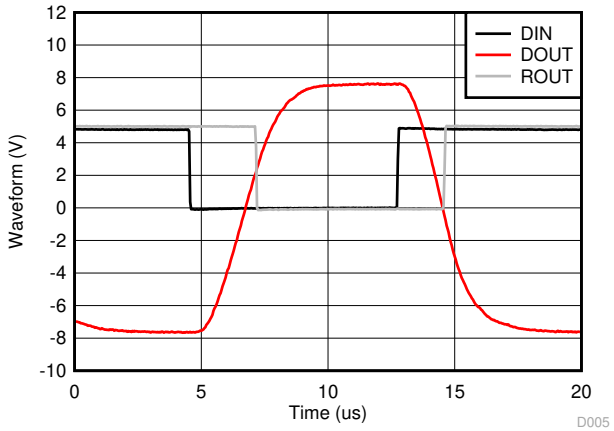
The capacitor type used for C1–C4 is not critical for proper operation. The MAX232E requires 1µF capacitors, although capacitors up to 10µF can be used without harm. Ceramic dielectrics are suggested for capacitors. When using the minimum recommended capacitor values, make sure the capacitance value does not degrade excessively as the operating temperature varies. If in doubt, use capacitors with a larger (for example, 2×) nominal value. The capacitors' effective series resistance (ESR), which usually rises at low temperatures, influences the amount of ripple on V+ and V–.

Use larger capacitors (up to 10µF) to reduce the output impedance at $V_{S+}$ and $V_{S–}$.

Bypass $V_{CC}$ to ground with at least 1 µF. In applications sensitive to power-supply noise generated by the charge pumps, decouple $V_{CC}$ to ground with a capacitor the same size as (or larger than) the charge-pump capacitors (C1–C4).

### 7.2.3 Application Curve

Loopback waveform connects DOUT to RIN.




Date Rate = 120 kbit/s, $C_L$ = 1 nF

**Figure 7-2. Loopback Waveforms**

## 7.3 Power Supply Recommendations

The $V_{CC}$ voltage should be connected to the same power source used for logic device connected to DIN and ROUT pins. $V_{CC}$ should be between 4.5V and 5.5V.

## 7.4 Layout

### 7.4.1 Layout Guidelines

Keep the external capacitor traces short. This is more important on C1 and C2 nodes that have the fastest rise and fall times. Make the impedance from MAX232E ground pin and circuit board ground plane as low as possible for best ESD performance. Use wide metal and multiple vias on both sides of ground pin.

### 7.4.2 Layout Example

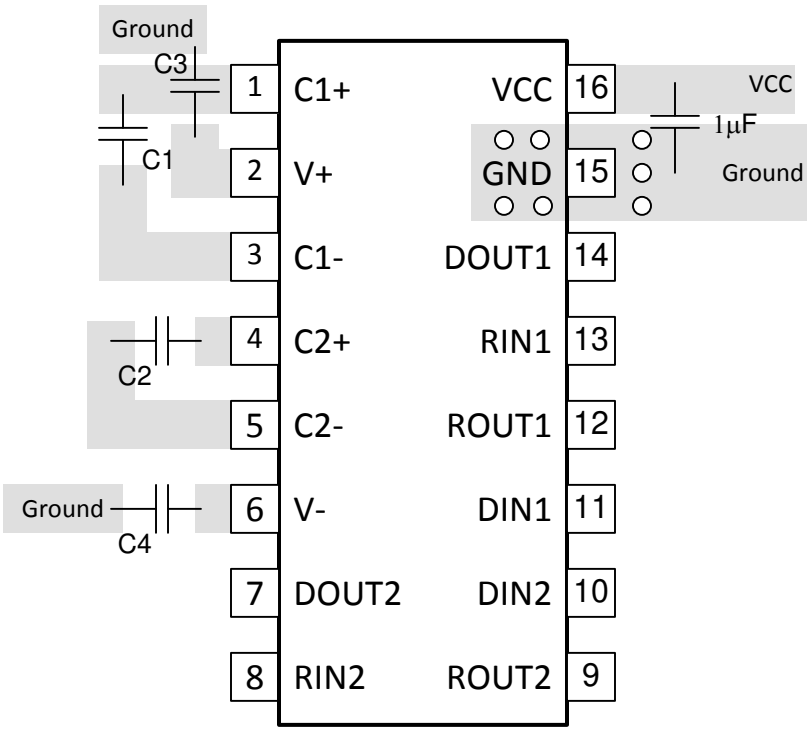



**Figure 7-3. MAX232E Layout**

# 8 Device and Documentation Support

## 8.1 Receiving Notification of Documentation Updates

To receive notification of documentation updates, navigate to the device product folder on ti.com. Click on *Subscribe to updates* to register and receive a weekly digest of any product information that has changed. For change details, review the revision history included in any revised document.

## 8.2 Support Resources

TI E2E™ support forums are an engineer's go-to source for fast, verified answers and design help — straight from the experts. Search existing answers or ask your own question to get the quick design help you need.

Linked content is provided "AS IS" by the respective contributors. They do not constitute TI specifications and do not necessarily reflect TI's views; see TI's Terms of Use.

## 8.3 Trademarks

TI E2E™ is a trademark of Texas Instruments.
All trademarks are the property of their respective owners.

## 8.4 Electrostatic Discharge Caution

This integrated circuit can be damaged by ESD. Texas Instruments recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

## 8.5 Glossary

| | |
|---|---|
| TI Glossary | This glossary lists and explains terms, acronyms, and definitions. |

# 9 Revision History

NOTE: Page numbers for previous revisions may differ from page numbers in the current version.

**Changes from Revision C (August 2016) to Revision D (February 2024)** — **Page**

- Changed the Device Information table to the *Package Information* table ... 1
- Changed the *Thermal Information* table ... 5

**Changes from Revision B (November 2009) to Revision C (August 2016)** — **Page**

- Added *ESD Ratings* table, *Feature Description* section, *Device Functional Modes*, *Application and Implementation* section, *Power Supply Recommendations* section, *Layout* section, *Device and Documentation Support* section, and *Mechanical, Packaging, and Orderable Information* section ... 1
- Deleted "±30-V Input Levels" from *Features* ... 1
- Deleted *Ordering Information* table; see POA at the end of the data sheet ... 1
- Added MIN value ±3 to "Receiver input voltage (RIN1, RIN2) row in *Recommended Operating Conditions* ... 4
- Changed $R_{\theta JA}$ values in *Thermal Information* ... 5
- Deleted table note 3 from *Receiver Section Electrical Characteristics* ... 5
- Added a new row to the *Function Table for Each Receiver* ... 11

# 10 Mechanical, Packaging, and Orderable Information

The following pages include mechanical, packaging, and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-hand navigation.

## PACKAGING INFORMATION

| Orderable Device | Status (1) | Package Type | Package Drawing | Pins | Package Qty | Eco Plan (2) | Lead finish/ Ball material (6) | MSL Peak Temp (3) | Op Temp (°C) | Device Marking (4/5) | Samples |
|---|---|---|---|---|---|---|---|---|---|---|---|
| MAX232ECDR | ACTIVE | SOIC | D | 16 | 2500 | RoHS & Green | NIPDAU | Level-1-260C-UNLIM | 0 to 70 | MAX232EC | Samples |
| MAX232EIDR | ACTIVE | SOIC | D | 16 | 2500 | RoHS & Green | NIPDAU | Level-1-260C-UNLIM | -40 to 85 | MAX232EI | Samples |
| MAX232EIDW | OBSOLETE | SOIC | DW | 16 | | TBD | Call TI | Call TI | -40 to 85 | MAX232EI | |
| MAX232EIDWR | ACTIVE | SOIC | DW | 16 | 2000 | RoHS & Green | NIPDAU | Level-1-260C-UNLIM | -40 to 85 | MAX232EI | Samples |
| MAX232EIN | ACTIVE | PDIP | N | 16 | 25 | RoHS & Green | NIPDAU | N / A for Pkg Type | -40 to 85 | MAX232EIN | Samples |
| MAX232EINE4 | ACTIVE | PDIP | N | 16 | 25 | RoHS & Green | NIPDAU | N / A for Pkg Type | -40 to 85 | MAX232EIN | Samples |
| MAX232EIPWR | ACTIVE | TSSOP | PW | 16 | 2000 | RoHS & Green | NIPDAU | Level-1-260C-UNLIM | -40 to 85 | MB232EI | Samples |

(1) The marketing status values are defined as follows:
**ACTIVE:** Product device recommended for new designs.
**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.
**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.
**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.
**OBSOLETE:** TI has discontinued the production of the device.

(2) **RoHS:** TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".
**RoHS Exempt:** TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.
**Green:** TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

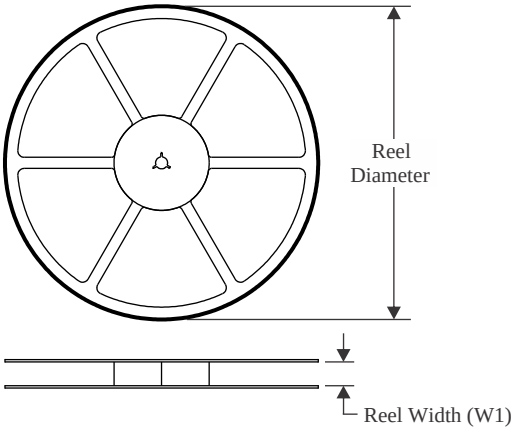
(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

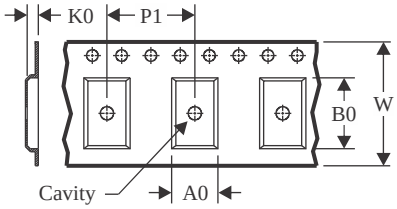
**(6)** Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

## TAPE AND REEL INFORMATION

**REEL DIMENSIONS**

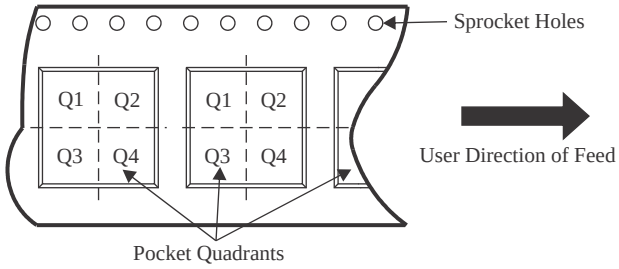



**TAPE DIMENSIONS**




| | |
|---|---|
| A0 | Dimension designed to accommodate the component width |
| B0 | Dimension designed to accommodate the component length |
| K0 | Dimension designed to accommodate the component thickness |
| W | Overall width of the carrier tape |
| P1 | Pitch between successive cavity centers |

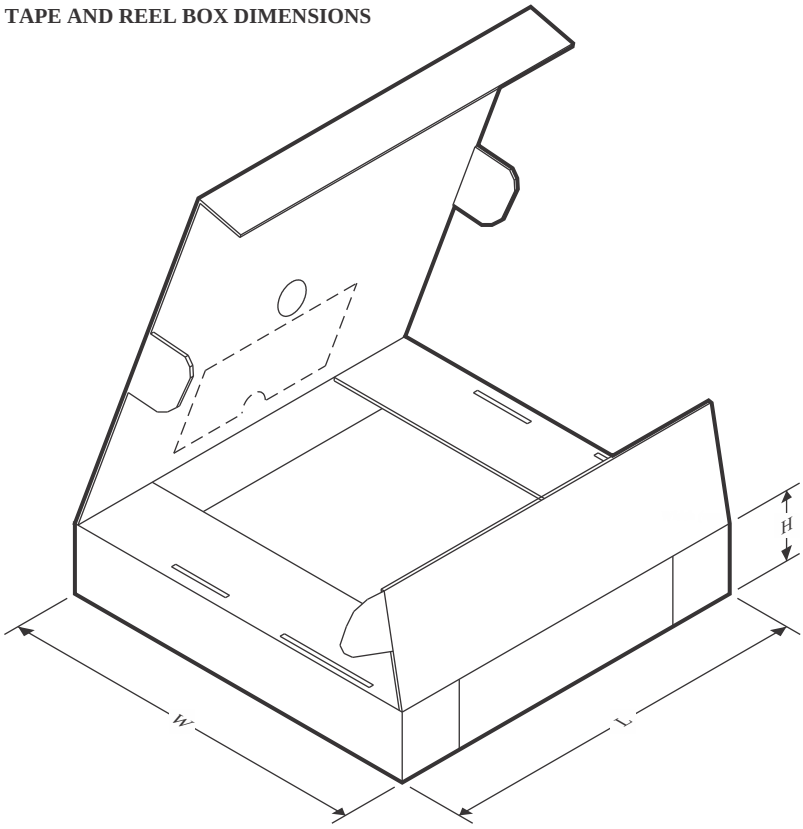
**QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE**




*All dimensions are nominal

| Device | Package Type | Package Drawing | Pins | SPQ | Reel Diameter (mm) | Reel Width W1 (mm) | A0 (mm) | B0 (mm) | K0 (mm) | P1 (mm) | W (mm) | Pin1 Quadrant |
|---|---|---|---|---|---|---|---|---|---|---|---|---|
| MAX232ECDR | SOIC | D | 16 | 2500 | 330.0 | 16.4 | 6.5 | 10.3 | 2.1 | 8.0 | 16.0 | Q1 |
| MAX232EIDR | SOIC | D | 16 | 2500 | 330.0 | 16.4 | 6.5 | 10.3 | 2.1 | 8.0 | 16.0 | Q1 |
| MAX232EIDWR | SOIC | DW | 16 | 2000 | 330.0 | 16.4 | 10.75 | 10.7 | 2.7 | 12.0 | 16.0 | Q1 |
| MAX232EIPWR | TSSOP | PW | 16 | 2000 | 330.0 | 12.4 | 6.9 | 5.6 | 1.6 | 8.0 | 12.0 | Q1 |

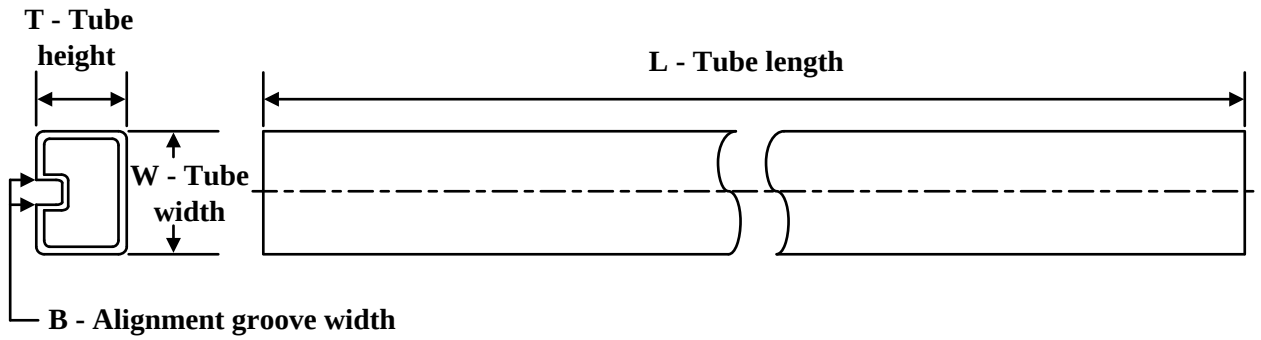
TAPE AND REEL BOX DIMENSIONS




*All dimensions are nominal

| Device | Package Type | Package Drawing | Pins | SPQ | Length (mm) | Width (mm) | Height (mm) |
|---|---|---|---|---|---|---|---|
| MAX232ECDR | SOIC | D | 16 | 2500 | 356.0 | 356.0 | 35.0 |
| MAX232EIDR | SOIC | D | 16 | 2500 | 356.0 | 356.0 | 35.0 |
| MAX232EIDWR | SOIC | DW | 16 | 2000 | 350.0 | 350.0 | 43.0 |
| MAX232EIPWR | TSSOP | PW | 16 | 2000 | 356.0 | 356.0 | 35.0 |

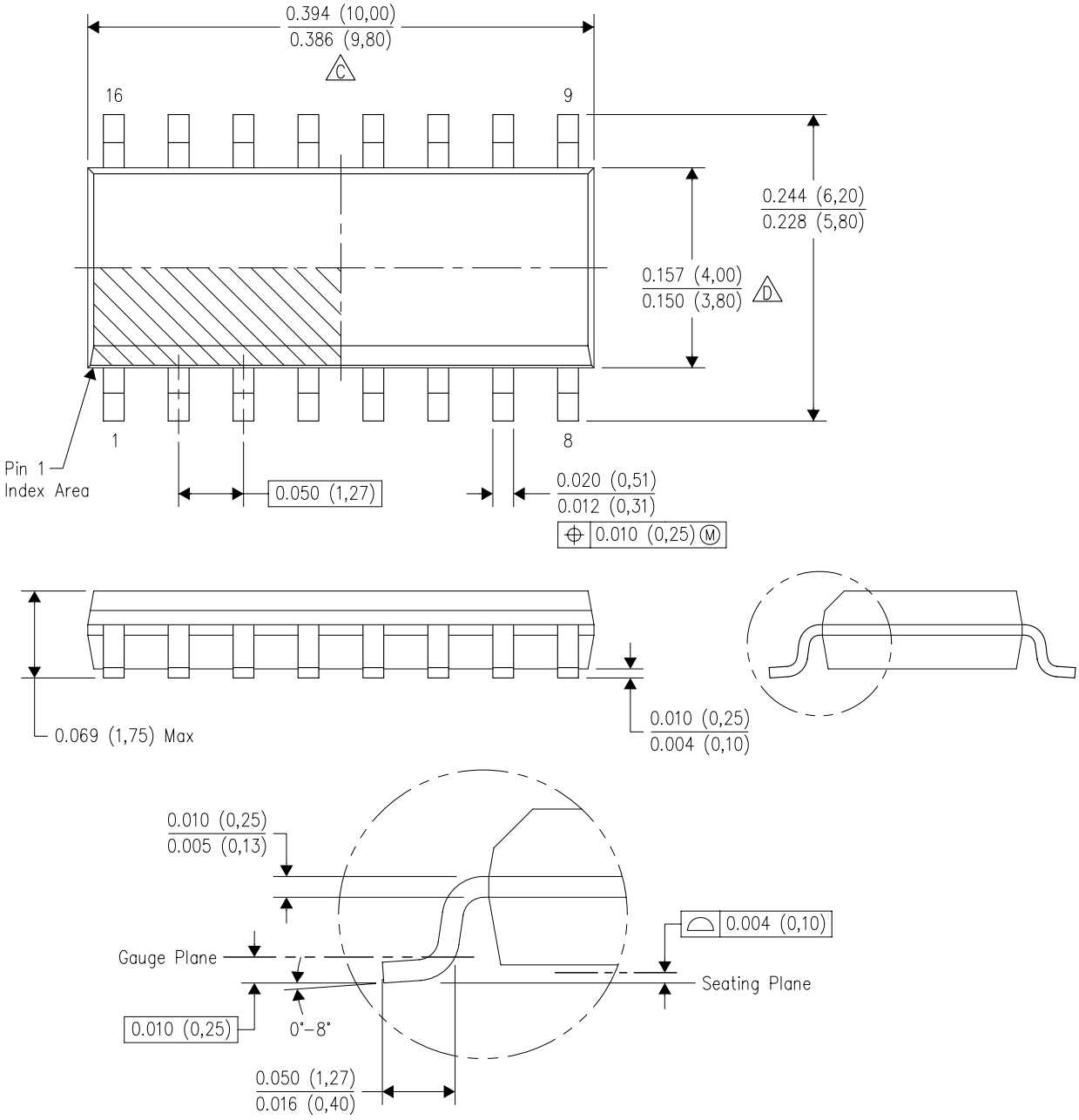
## TUBE




*All dimensions are nominal

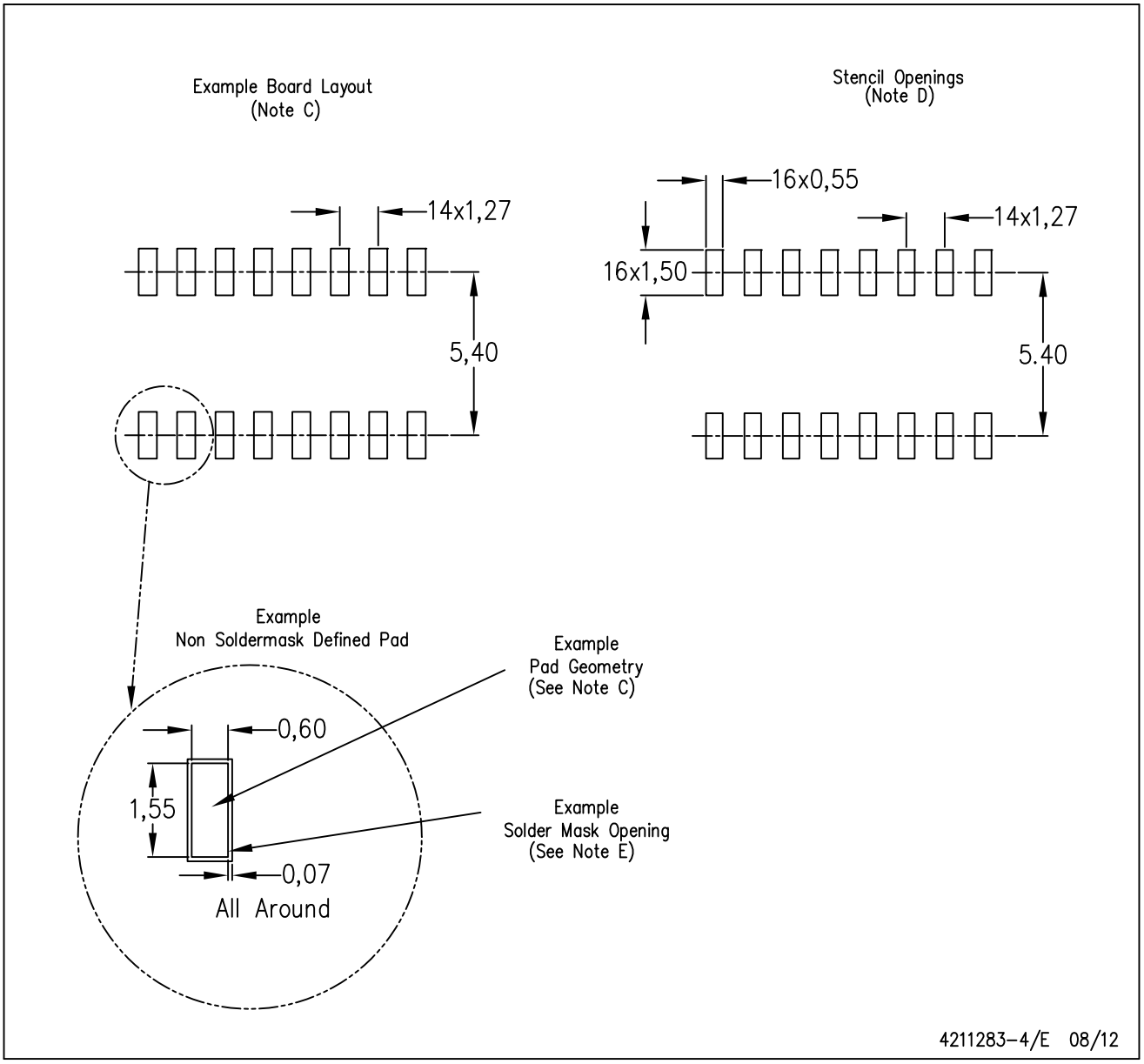
| Device | Package Name | Package Type | Pins | SPQ | L (mm) | W (mm) | T (µm) | B (mm) |
|---|---|---|---|---|---|---|---|---|
| MAX232EIN | N | PDIP | 16 | 25 | 506 | 13.97 | 11230 | 4.32 |
| MAX232EINE4 | N | PDIP | 16 | 25 | 506 | 13.97 | 11230 | 4.32 |

D (R–PDSO–G16) PLASTIC SMALL OUTLINE




NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
D. Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
E. Reference JEDEC MS–012 variation AC.

D (R–PDSO–G16) PLASTIC SMALL OUTLINE



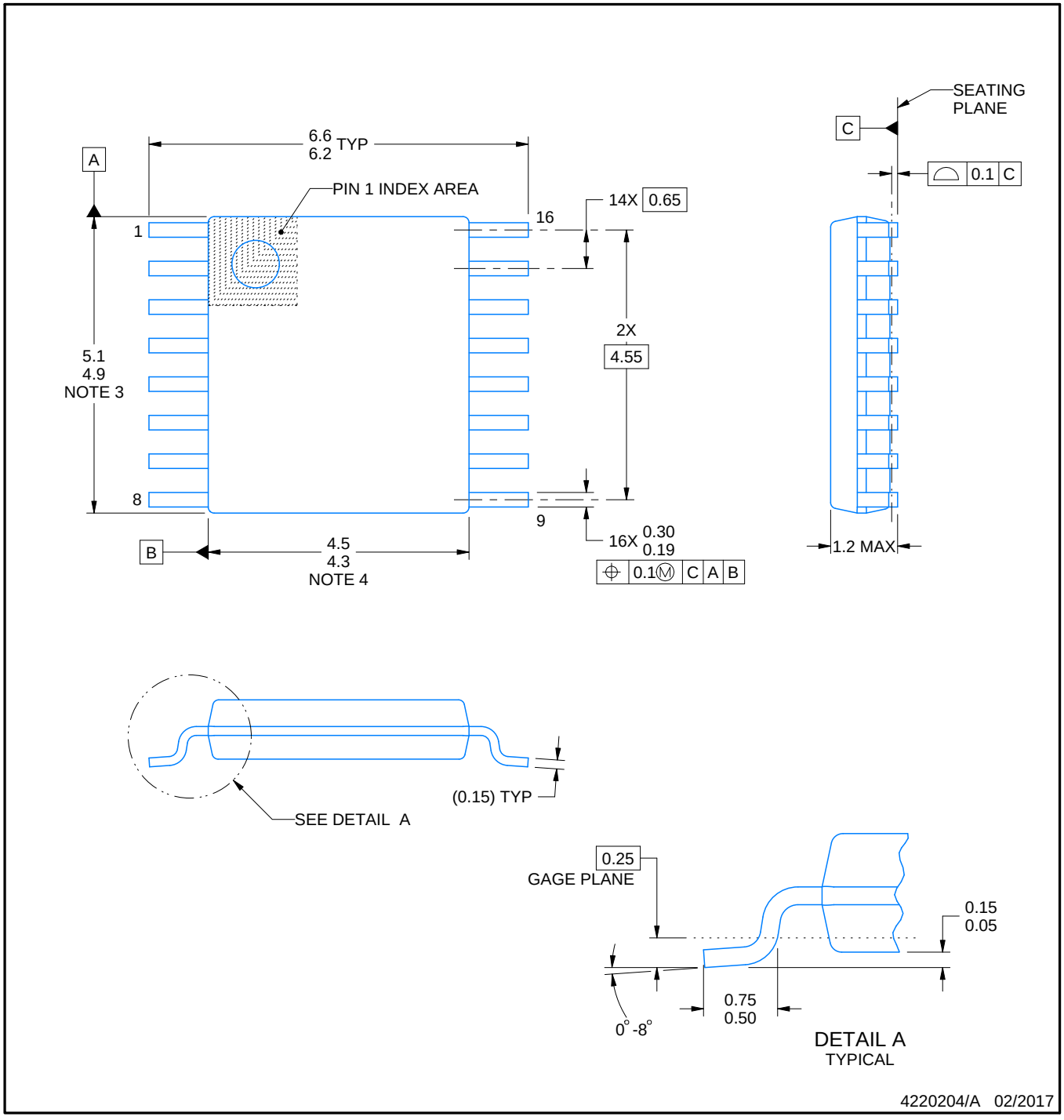

NOTES:
A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Publication IPC–7351 is recommended for alternate designs.
D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC–7525 for other stencil recommendations.
E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

# PACKAGE OUTLINE

## PW0016A

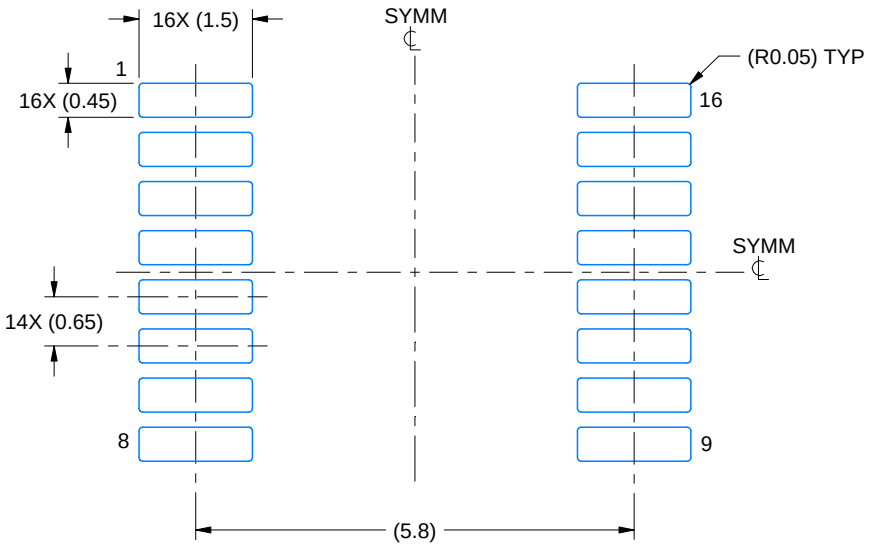
## TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE

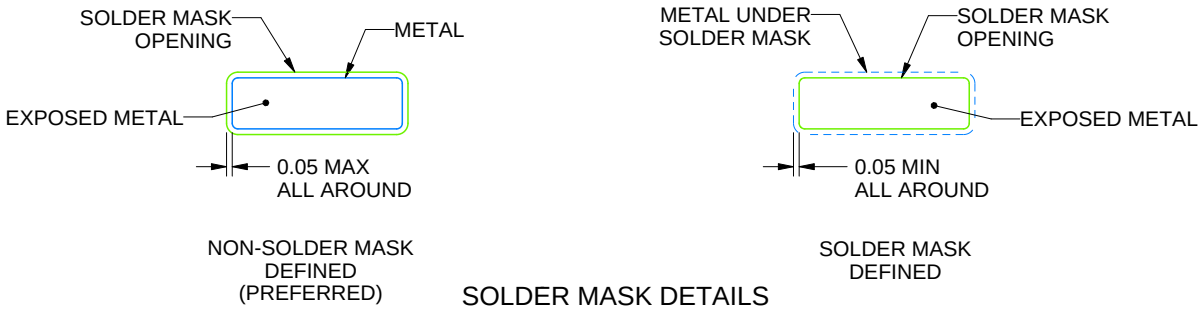



NOTES:

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm per side.
5. Reference JEDEC registration MO-153.




LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE: 10X

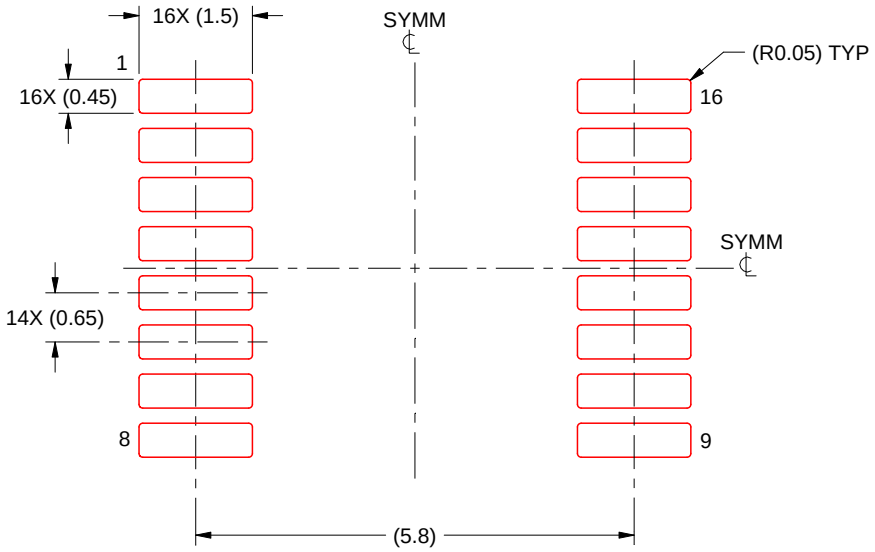



SOLDER MASK DETAILS

4220204/A 02/2017

NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.
7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.




SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE: 10X

4220204/A 02/2017

NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

# GENERIC PACKAGE VIEW

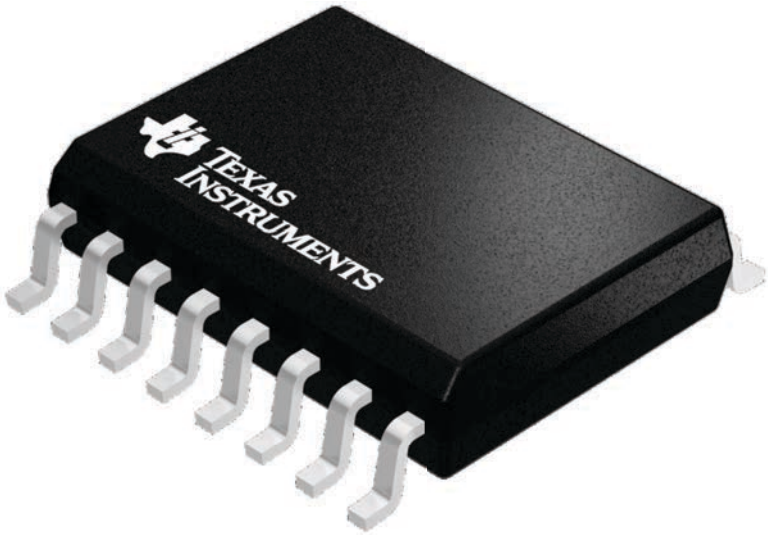
## DW 16

## SOIC - 2.65 mm max height

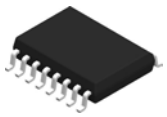
**7.5 x 10.3, 1.27 mm pitch**

SMALL OUTLINE INTEGRATED CIRCUIT

This image is a representation of the package family, actual package may vary.
Refer to the product data sheet for package details.




4224780/A

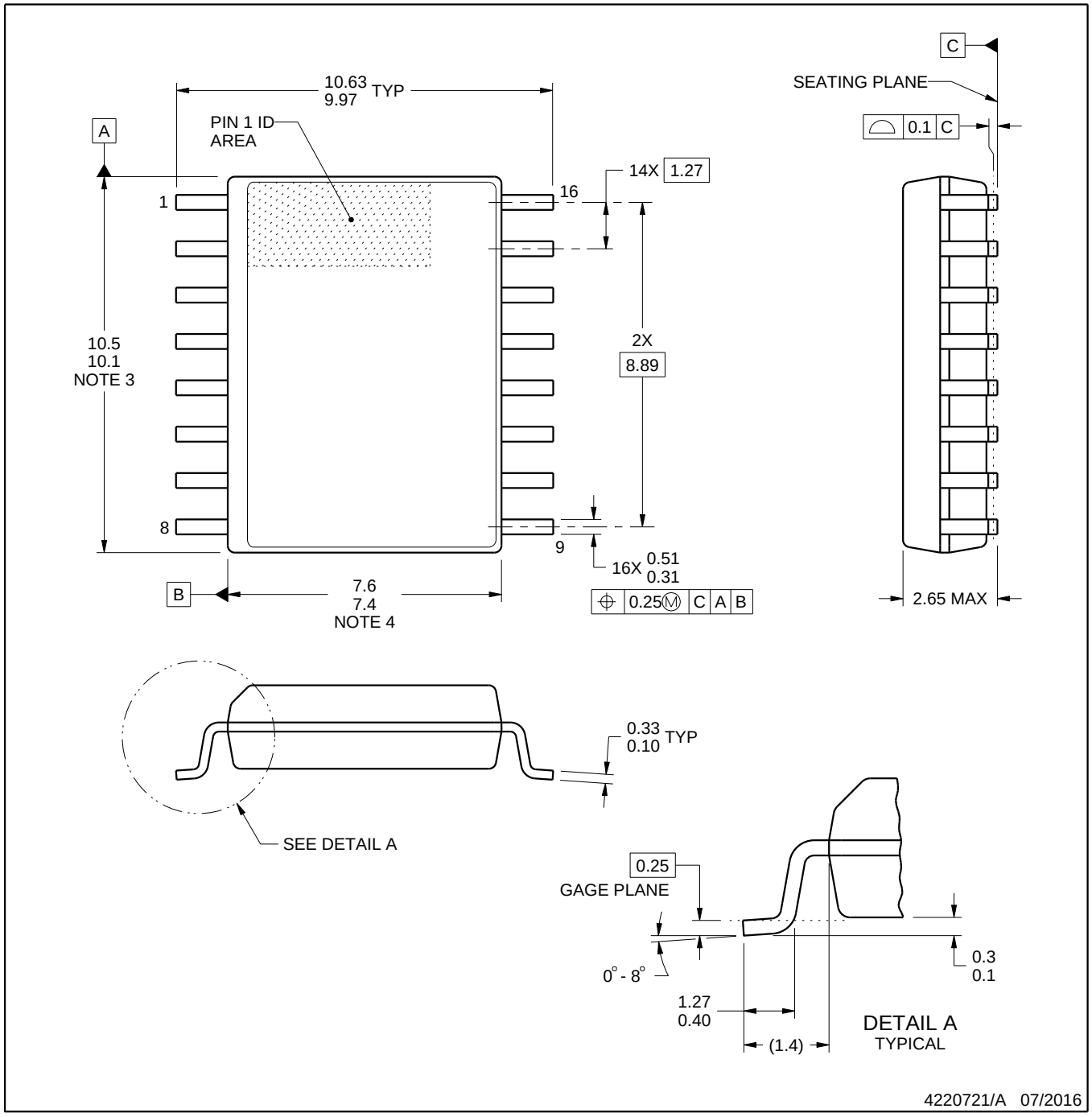


# PACKAGE OUTLINE

## DW0016A

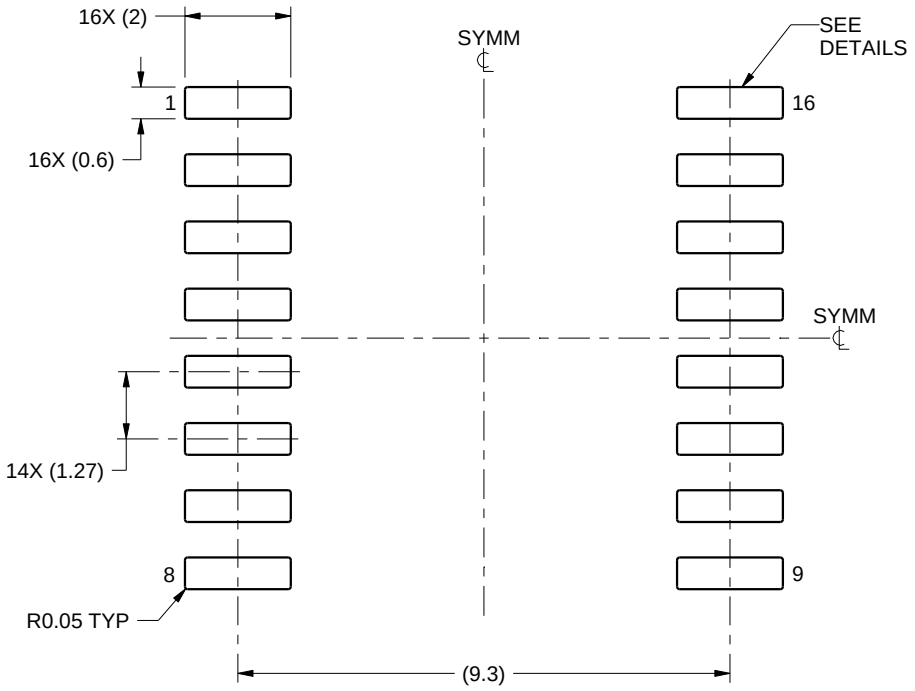
## SOIC - 2.65 mm max height

SOIC

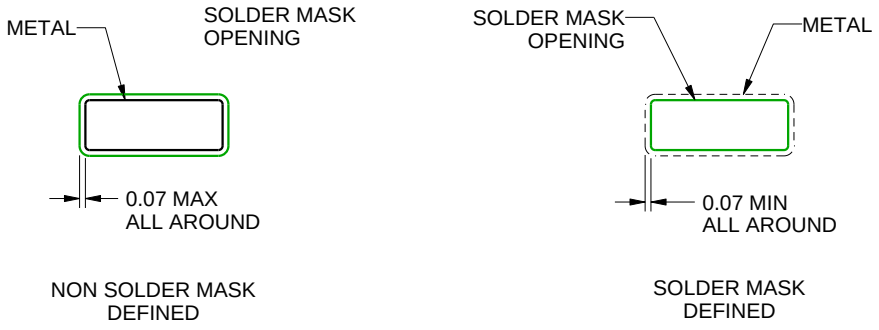



NOTES:

1. All linear dimensions are in millimeters. Dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm, per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm, per side.
5. Reference JEDEC registration MS-013.




LAND PATTERN EXAMPLE
SCALE:7X

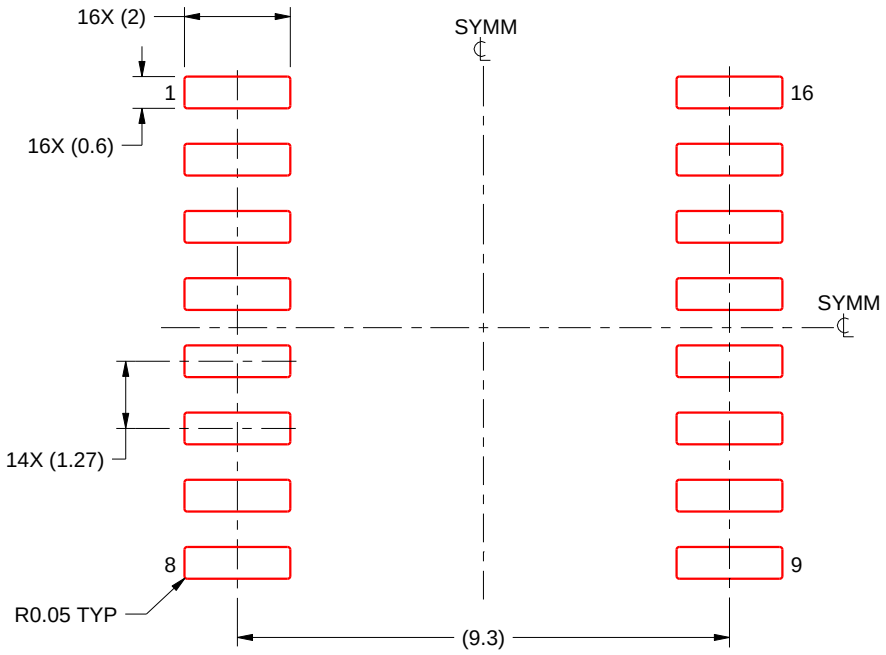



SOLDER MASK DETAILS

4220721/A 07/2016

NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.
7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.




SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE:7X

4220721/A 07/2016

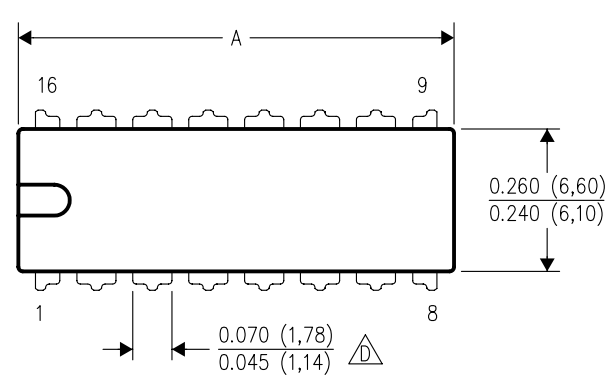
NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

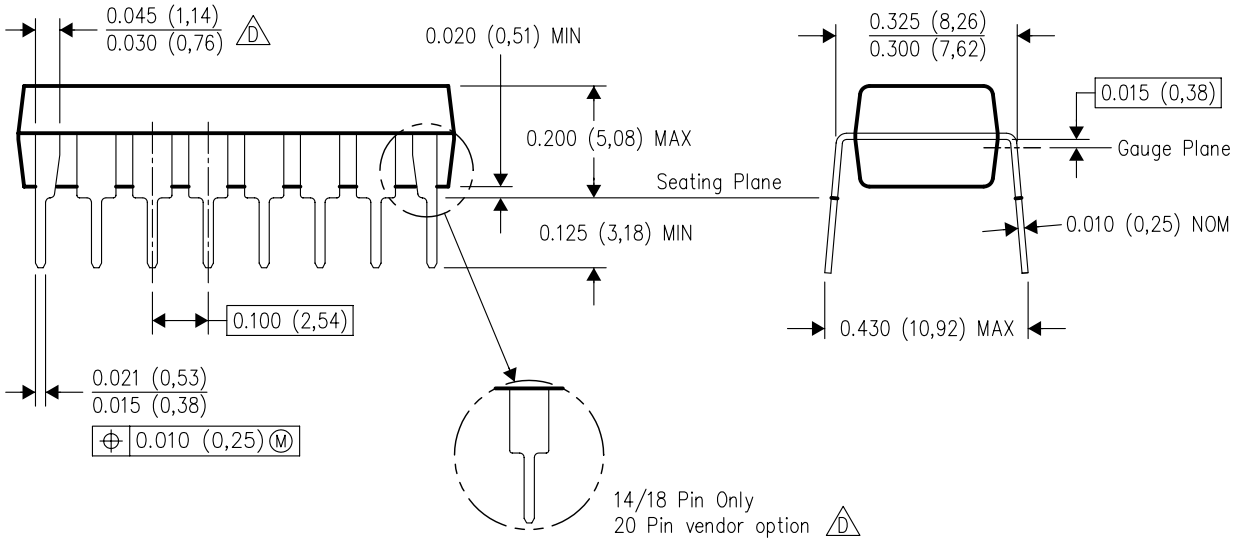
## N (R–PDIP–T**)

## PLASTIC DUAL–IN–LINE PACKAGE

16 PINS SHOWN




| DIM \ PINS ** | 14 | 16 | 18 | 20 |
|---|---|---|---|---|
| A MAX | 0.775 (19,69) | 0.775 (19,69) | 0.920 (23,37) | 1.060 (26,92) |
| A MIN | 0.745 (18,92) | 0.745 (18,92) | 0.850 (21,59) | 0.940 (23,88) |
| MS–001 VARIATION (C) | AA | BB | AC | AD |




4040049/E 12/2002

NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. Falls within JEDEC MS–001, except 18 and 20 pin minimum body length (Dim A).
D. The 20 pin end lead shoulder width is a vendor option, either half or full width.

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